

Customer Information Notification

Issue Date: 22-Dec-2018 Effective Date: 22-Jan-2019

Dear Emma Tempest,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP.

For detailed information we invite you to <u>view this</u> notification online

This notice is NXP Company Proprietary.

2018110271



[X] Test

Location

[] Design

Change Category [] Wafer Fab Process [] [] Product Marking Assembly Process

[] Mechanical []Test []Errata
Assembly Specification Process

Materials

[] Wafer Fab Location

[] [] [] [] Test [] Electrical

Assembly Packing/Shipping/Labeling Equipment spec./Test

Assembly Packing/Shipping/Labeling Equipment spec./Tes Location coverage

[] Other

[] Firmware

[] Wafer Fab Materials

MPC5748G 256MAPBGA and 324MAPBGA Site Expansion : Burn-In from TTM to TTTJ, and Final Test from NXP-ATKL to NXP-ATTJ

Description

NXP Semiconductors announces the Burn in and Final Test site expansion for the MPC5748G products (0N78S and 1N81M) 256MAPBGA and 324MAPBGA packages associated with this notification

- 1. Burn-in site expansion from the current Trio Tech Malaysia (TTM), Petaling Jaya, Malaysia Burn-in site to the Trio Tech Tianjin (TTTJ), Tianjin, China Burn-in site.
- 2. Final Test site expansion from the current NXP-ATKL, Petaling Jaya, Malaysia Final Test site to the NXP-ATTJ, Tianjin, China Final Test site.

Site expansion was successfully qualified adhering to NXP specifications.

Corresponding ZVEI Delta Qualification Matrix ID: SEM-TF-01

Please see the attached file(s) for additional details.

Reason

Site expansion qualification is required for manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Affected products and sales history information: see attached file

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality Support Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Chen Tat Tan
Position Product Engineer
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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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